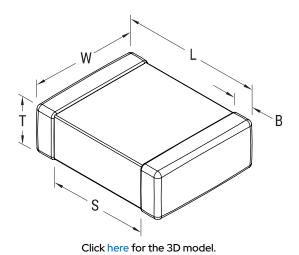


C0603C680K2TAC7411

SMD Comm X8G HT150C, Ceramic, 68 pF, 10%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.5 mm



General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	3.7 mg
Shelf Life	78 Weeks
MSL	1

mensions		Sp
nip Size	0603	Ca
	1.6mm +/-0.15mm	Me
	0.8mm +/-0.15mm	To
	0.8mm +/-0.07mm	Vo
	0.5mm MIN	Die
	0.35mm +/-0.15mm	Те
		Tei

Packaging Specifications TOP 222 Pa Pa

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ackaging	T&R, 330mm, Paper Tape
ackaging Quantity	15000

Specifications	
Capacitance	68 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	10%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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